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SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## AOD4185(MS)

Product specification

**Features**

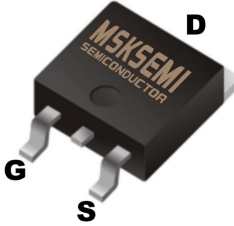
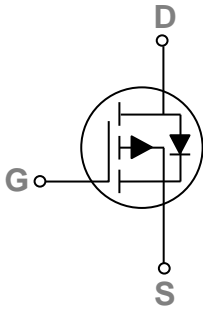

- -40V,-40A, RDS(ON) =12mΩ@VGS = -10V
- Fast switching
- Green Device Available

**Applications**

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

BVDSS	BVDSS	ID
-40V	12mΩ	-40A

**Reference News**

PACKAGE OUTLINE	Pin Configuration	Marking
 <p>TO-252</p>		 <p>Note:****Representative productioncycle</p>

**Absolute Maximum Ratings**Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> =25°C)	-40	A
	Drain Current - Continuous (T <sub>C</sub> =100°C)	-31	A
I <sub>DM</sub>	Drain Current - Pulsed <sup>1</sup>	-110	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	62	W
	Power Dissipation - Derate above 25°C	0.59	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.7	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^{\circ}C/W$

**Electrical Characteristics ( $T_J=25^{\circ}C$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-40	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-40V, V_{GS}=0V, T_J=25^{\circ}C$	---	---	-1	$\mu A$
		$V_{DS}=-32V, V_{GS}=0V, T_J=125^{\circ}C$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-10A$	---	12	15	m $\Omega$
		$V_{GS}=-4.5V, I_D=-8A$	---	13	23	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	-1.5	-2.5	V
gfs	Forward Transconductance	$V_{DS}=-10V, I_D=-10A$	---	13	---	S

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=-32V, V_{GS}=-4.5V, I_D=-10A$	---	22.2	---	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	8.2	---	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	8.8	---	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=-20V, V_{GS}=-10V, R_G=6\Omega$ $I_D=-1A$	---	23	---	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	10	---	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	135	---	
$T_f$	Fall Time <sup>3, 4</sup>		---	46	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-25V, V_{GS}=0V, F=1MHz$	---	2757	---	pF
$C_{oss}$	Output Capacitance		---	240	---	
$C_{riss}$	Reverse Transfer Capacitance		---	137	---	

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{ Force Current}$	---	---	-40	A
$I_{SM}$	Pulsed Source Current		---	---	-80	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^{\circ}C$	---	---	-1.2	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=51A, R_G=25\Omega, \text{ Starting } T_J=25^{\circ}C$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.06	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =10A	---	24	30	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A	---	25	40	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0	1.6	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.6	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =8A	---	11	---	S

**Dynamic and switching Characteristics**

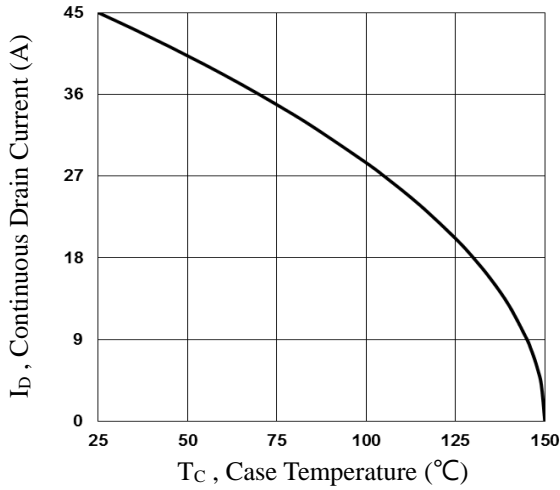
Q <sub>g</sub>	Total Gate Charge <sup>3,4</sup>	V <sub>DS</sub> =30V , V <sub>GS</sub> =10V , I <sub>D</sub> =10A	---	16.4	---	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3,4</sup>		---	3.1	---	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3,4</sup>		---	3.7	---	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3,4</sup>	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =6Ω I <sub>D</sub> =1A	---	4.6	---	ns
T <sub>r</sub>	Rise Time <sup>3,4</sup>		---	14.8	---	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3,4</sup>		---	27.2	---	
T <sub>f</sub>	Fall Time <sup>3,4</sup>		---	7.8	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , F=1MHz	---	1180	---	pF
C <sub>oss</sub>	Output Capacitance		---	80	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	52	---	

**Drain-Source Diode Characteristics and Maximum Ratings**

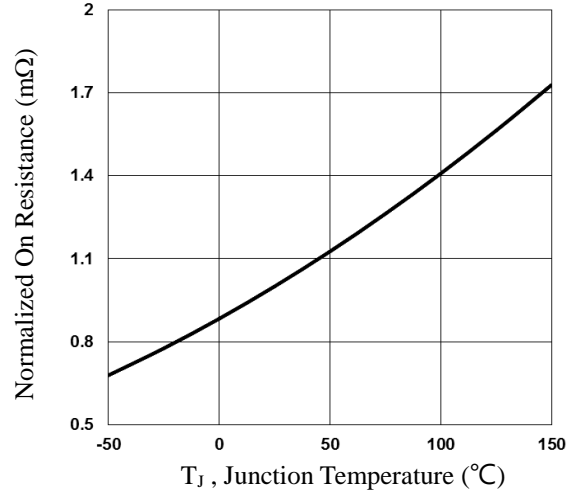
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	30	A
I <sub>SM</sub>	Pulsed Source Current		---	---	60	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C	---	---	1.2	V

Note :

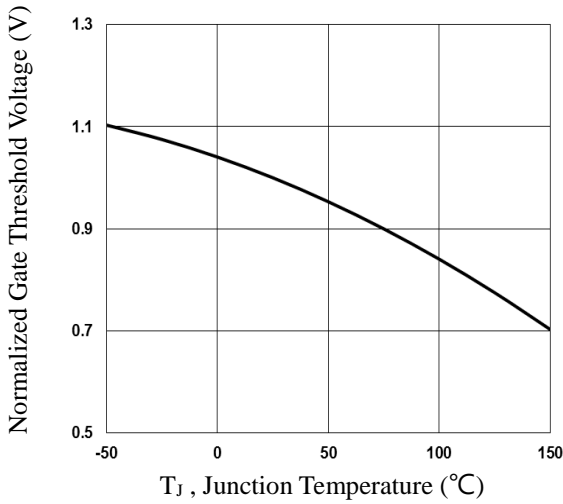
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=50V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=23A, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



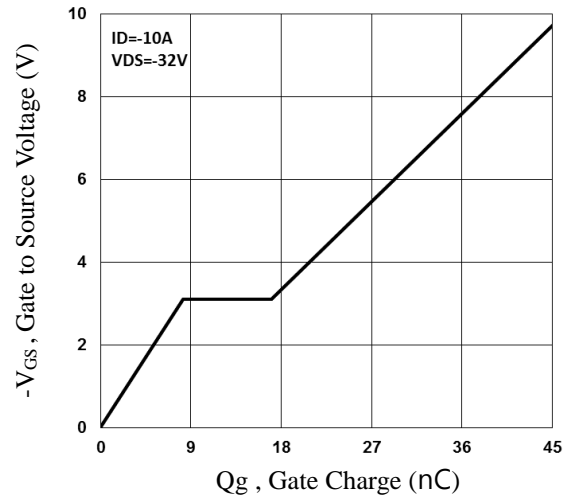
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



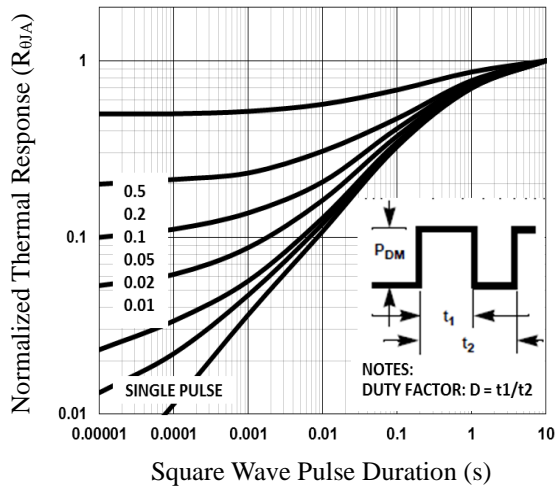
**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**



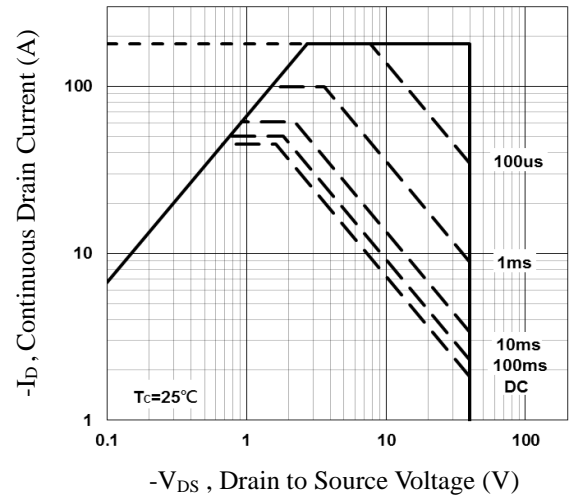
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



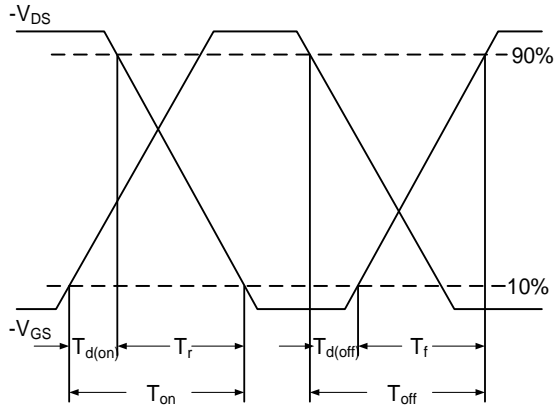
**Fig.4 Gate Charge Waveform**



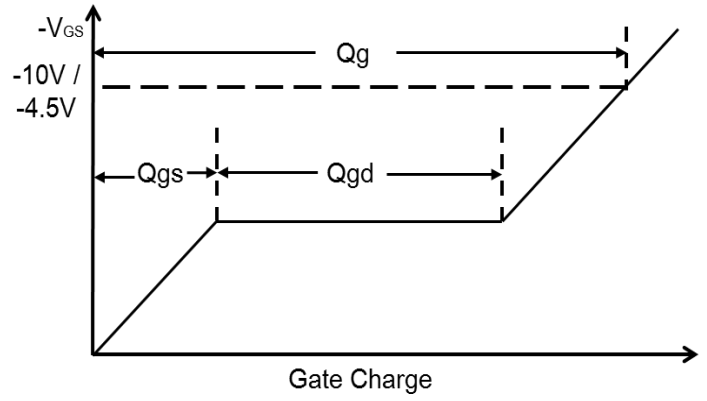
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

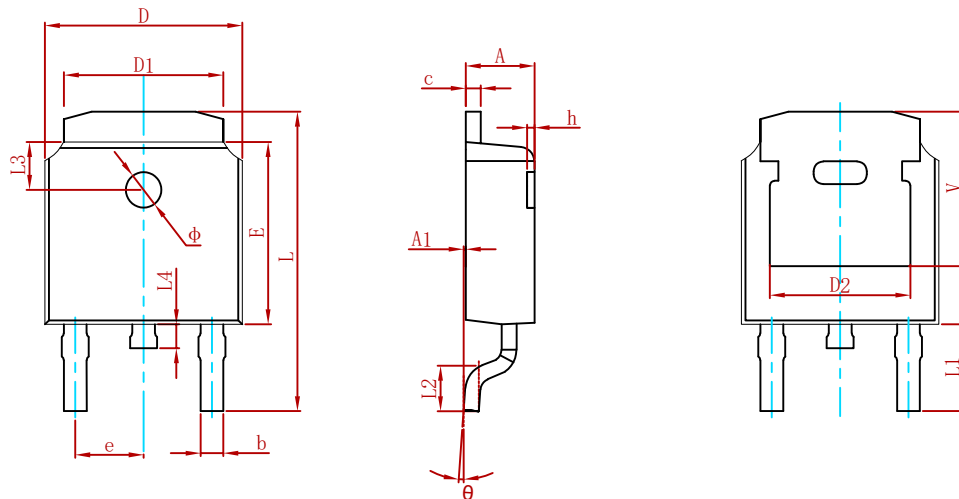


**Fig.7 Switching Time Waveform**



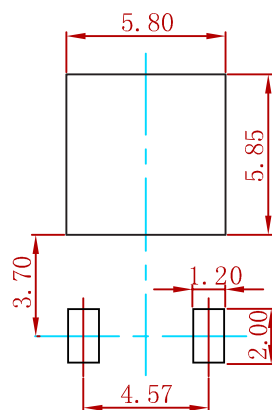
**Fig.8 Gate Charge Waveform**

**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

**Suggested Pad Layout**



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
AOD4185(MS)	TO-252	2500

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